

STM32WB07_WLCSP49_4L_IPD

MB2270

Table of contents

- Sheet 1: Project overview (this page)
- Sheet 2: STM32WB07_WLCSP49_RefBoard_IPD_4Layers

Legend

- General comment such as function title, configuration, ...
- Text to be added to silkscreen.
- Warning text.

A

Notes to generate the board layout.

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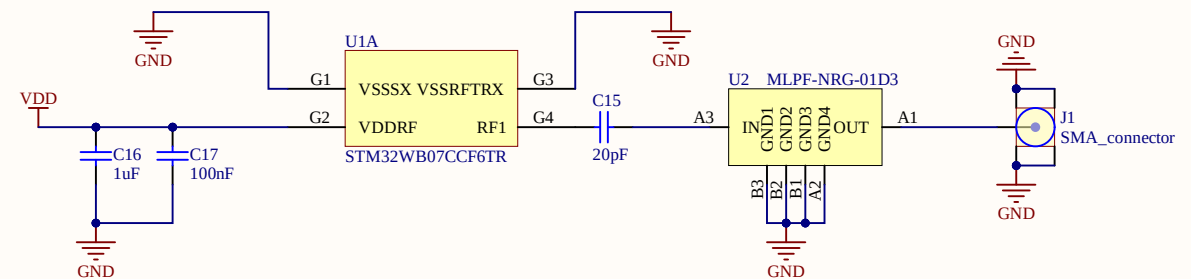
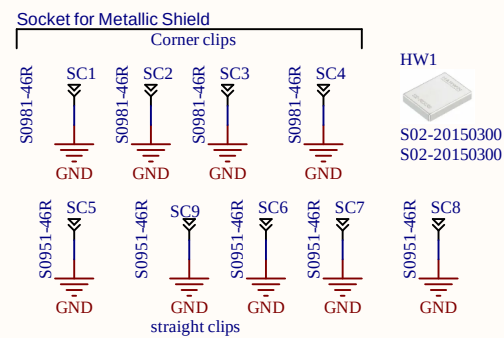
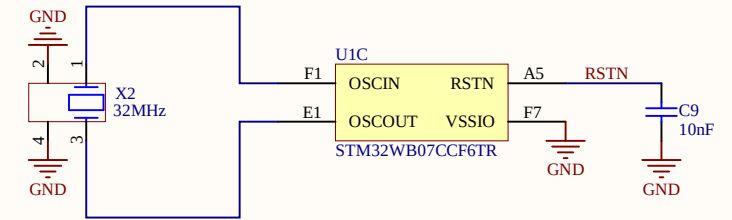
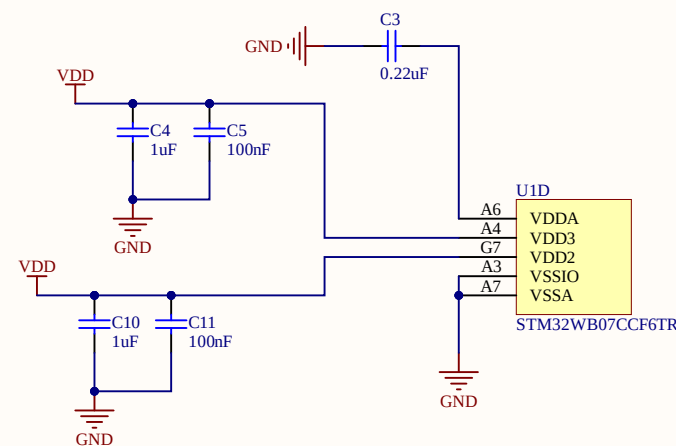
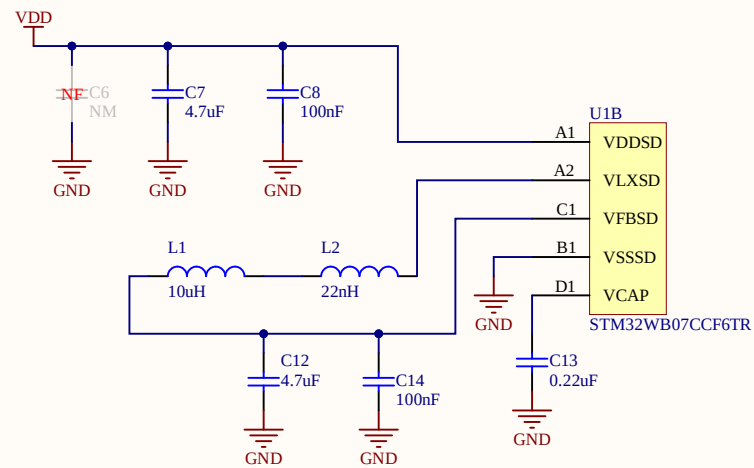
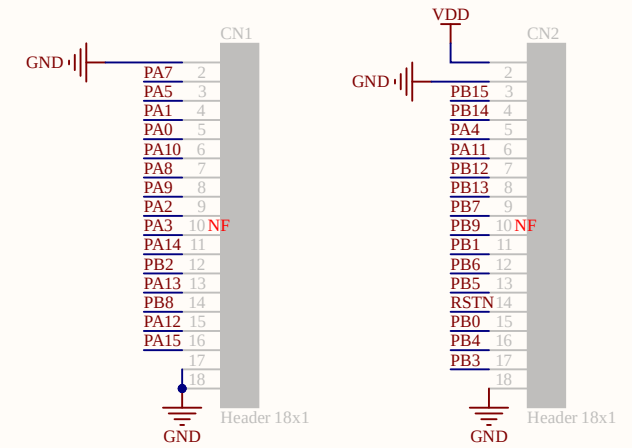
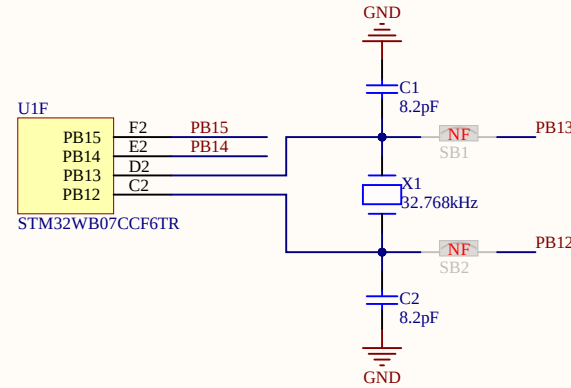
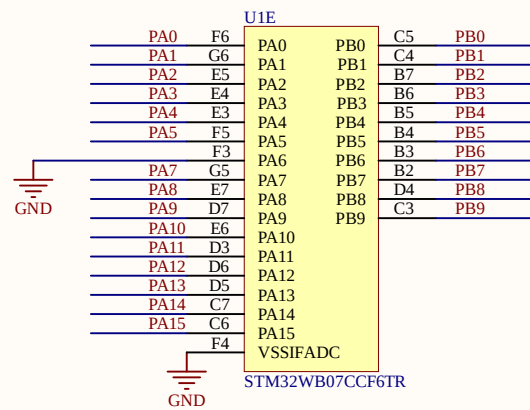
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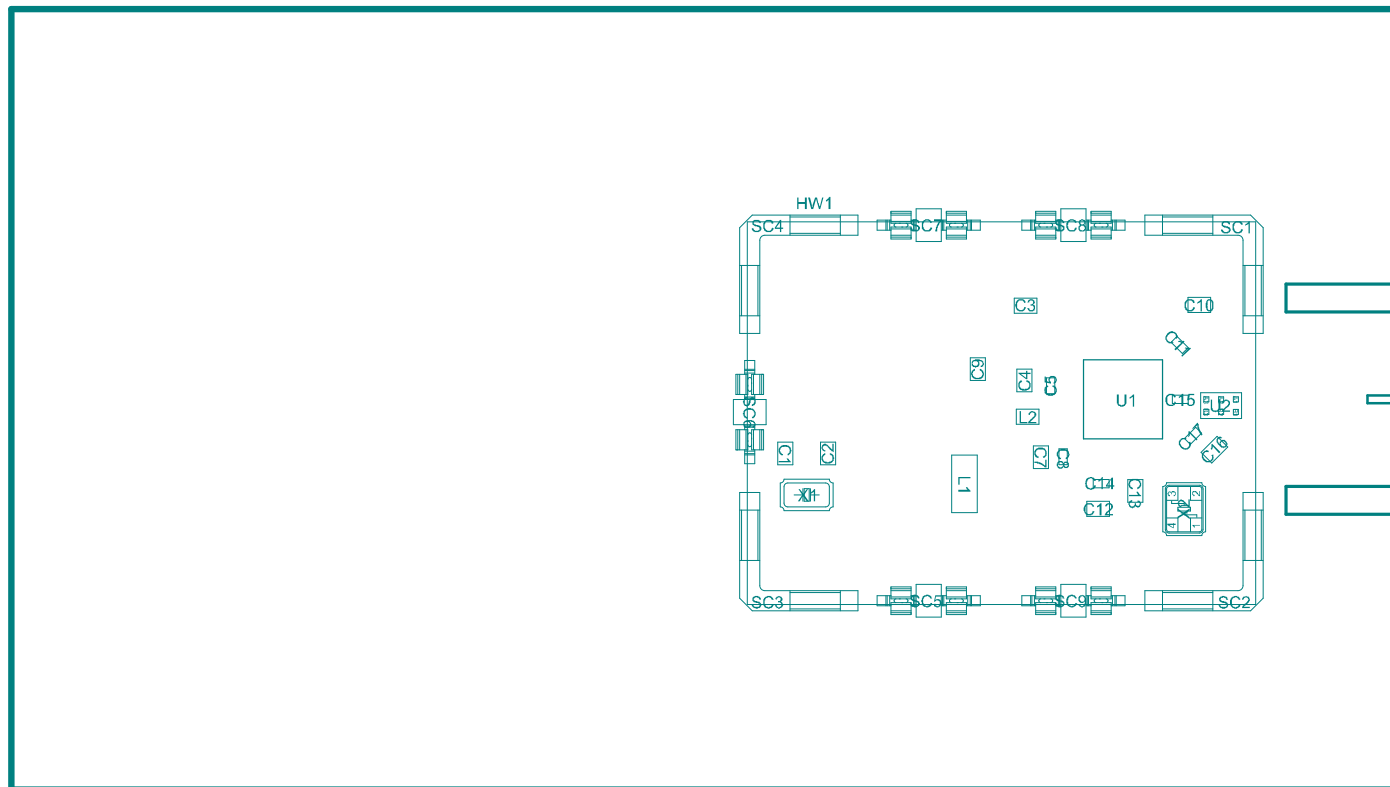
Top

STM32WB07_WLCSP49_RefBoard_IPD_4Layers.SchDoc

Title: Project overview		
Project: STM32WB07_WLCSP49_4L_IPD		
Variant: Variant A		
Revision: A-01		Reference: MB2270
Size: A4	Date: 26 August 2025	Sheet: 1 of 7







Project: STM32WB07_WLCSP49_4L_IPD

Layer: Mechanical 14

Gerber: .GM14

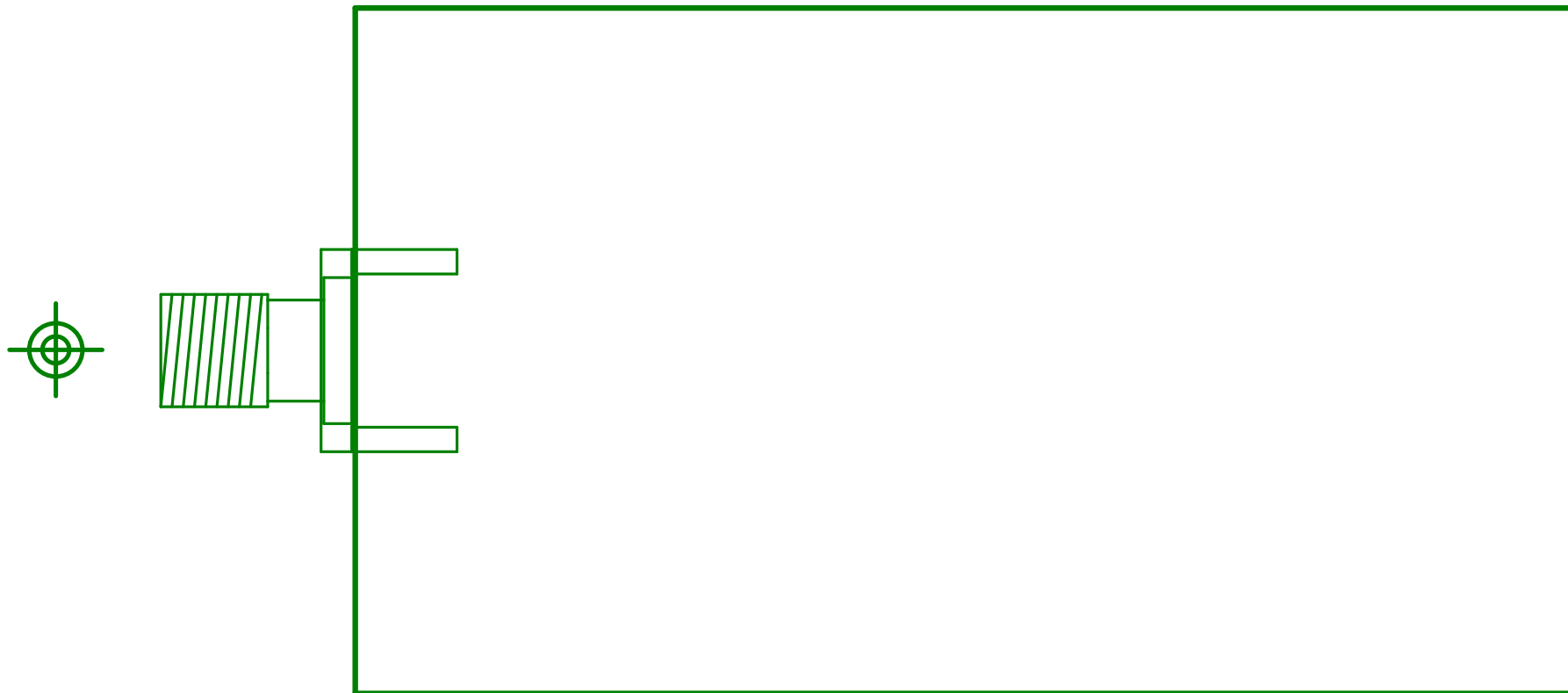
Variant: Variant A

Ref: MB2270

Date: 26 August 2025

Rev: A





Project: STM32WB07_WLCSP49_4L_IPD		
Layer: Mechanical 15	Gerber: .GM15	
Variant: Variant A	Ref: MB2270	
Date: 26 August 2025	Rev: A	



